

Applicant's arguments with respect to claims 25-27 and 31-33 have been considered but are moot in view of the new ground(s) of rejection.

Applicant has amended to include the limitation "wherein the first structure consists of a bond pad and the second structure consists of contact lines".

Claim Rejections - 35 USC § 103

The text of those sections of Title 35, U.S. Code not included in this action can be found in a prior Office action.

Claims 25-27 and 31-33 are rejected under 35 U.S.C. 103(a) as being unpatentable over Cheu et al (US 6,803,327) in view of Van der Putten .

Cheu et al discloses a bond pad and metal lines formed on a substrate and the metal lines are fine features compared to the bond pad and it is seen that the bond pad is more than two times as wide as the metal lines(Fig. 1 and col. 4, lines 28-49).

Cheu et al is silent with respect to the recited shape limitations.

Van der Putten discloses a shaped bond pad in which the base is wider than the top portion and the shape is pyramidal(Fig. 2, Fig. 3, and col. 3, lines 27-37 and 46-52). This decreases the likelihood of short-circuit(col. 1, lines 38-43). It is seen that the edges of the structure have portions which deviate from the pyramidal form, and these portions are recessed with respect to the form which would result from the structure having a pyramidal form, so that this would satisfy the limitation of recessed.

It would have been obvious to one of ordinary skill in the art at the time of the invention to have combined the shape of the bond pad taught by Van der Putten with the structure taught by Cheu et al in order to gain the benefit taught by Van der Putten of reduced short circuit.

Allowable Subject Matter

Claims 1, 3-4, 18-20, and 28-30 are allowed.

Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Caridad M. Everhart whose telephone number is 571-

Art Unit: 2895

272-1892. The examiner can normally be reached on Monday through Fridays 7:30-4:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, D. Richards can be reached on 571-272-1736. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

/Caridad Everhart/
Primary Examiner
AU 2895

11-9-2009